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INDIVIDUAL SPECIFICATION SHEET

Product Name: 0603 SMD Fuses

Part Number: F06T0.25

Revision: A







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Rev.	Effective Date	Changed Contents
Α	2020-9-25	Update Spedfications

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PREPEARED BY	APPROVED BY
杨崎	AMB



Description

F06T Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Electrical Characteristics					
Rated Current	1.0ln	2.5ln	3.0ln	4.0In	
250mA	4 hour minimum			5 sec maximum	

Features

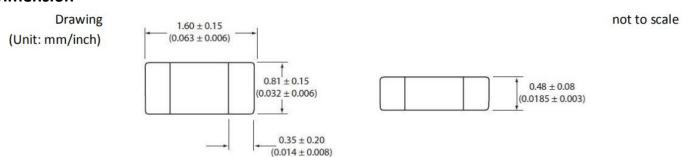
- Compatible with reflow and wave solder
- Excellent environmental integrity
- One time positive disconnect
- > Lead Free and Halogen free material

Specifications

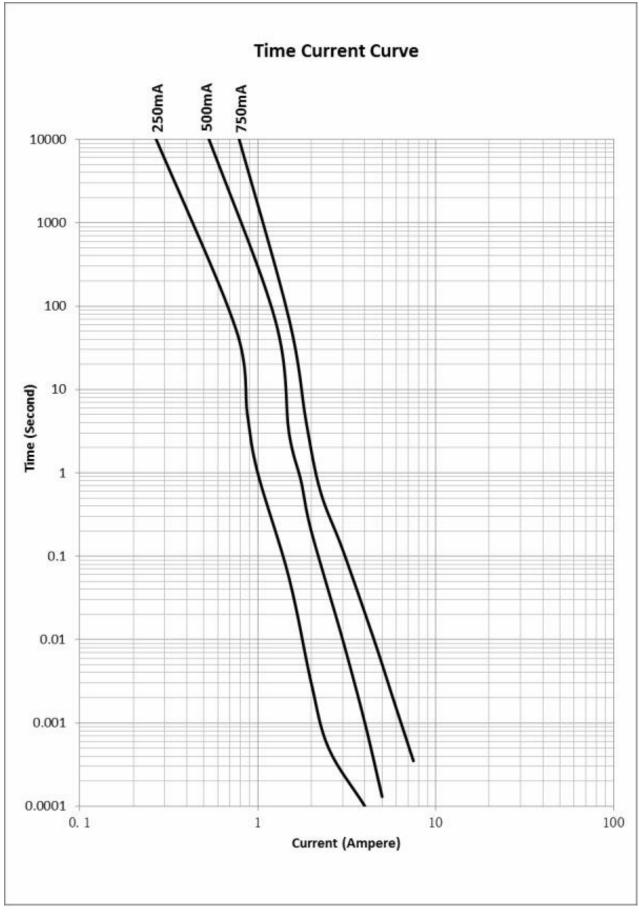
Specification							
5 (1)	Rated	Rated Current	Breaking	Typical Cold.	Typical	Typical Pre-	
Part No.	Voltage	(A)	Capacity (A)	Resistanc	Voltage Drop (mV)	Arcing I ² t (A ² Sec) ³	Alpha Mark
	DC			e (m Oh m a) 2	Diop (IIIV)	(A Sec)	
				(mOhms) 2			
F06T0.25	32V	0.25	50A	2300	850	0.0006	D

- 1. DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
- 2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25degrees
- 3. Typical Pre-arcing I2t are measured at 10In Current

Dimension



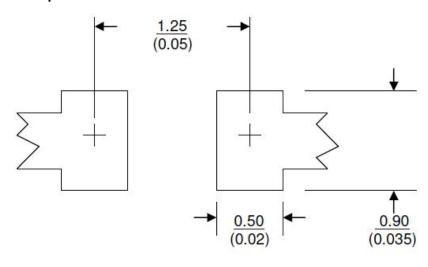




***250mA 产品为系统短路保护应用设计,最小保护电流 4.0 倍



Recommended land pattern



Unit: mm/inches

Soldering method

Wave solder

■ Reservoir temperature: 260°C

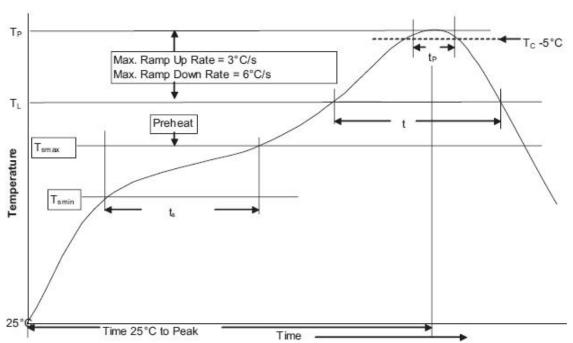
■ Time in reservoir: 10 seconds maximum

> Infrared reflow

■ Temperature: 260°C

■ Time: 30 seconds maximum

Solder reflow profile



Profile Feature		Lead(Pb) free solder
Preheat and soak	t and soak • Temperature min.(T _{smin})	
	Temperature max. (T _{smax})	200℃

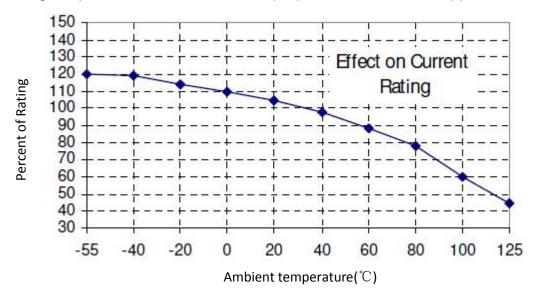


Time (T _{smin} to T _{smax}) (t _S)	60 - 120 Seconds		
Average ramp up rate T_{smax} to T_p	3°C / Second Max.		
Liquidous temperature (T _L)	217℃		
Time at liquidous (t∟)	60 - 150 Seconds		
Peak package body temperature (T _P)	260°C		
Time (t _P) within 5°C of the specified classification temperature (T _C)	30 Seconds		
Average ramp-down rate (T _P to T _{smax})	6°C / Second Max.		
Time (25°C to Peak Temperature)	8 Minutes Max.		

Temperature Derating Curve

Normal ambient temperature: 23+/-3°C

Operating temperature: -55 ~ 125°C, with proper correction factor applied



Package

5000 fuses on 8mm tape-and-reel on a 7 inch (178mm) reel per EIA Standard 481.

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